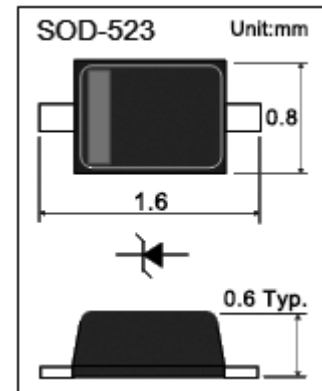


Small Signal Schottky DIODE

- ◇ Low Forward Voltage Drop
- ◇ **SOD523** Micro SMD package
- ◇ RoHS compliant / Green EMC
- ◇ Matte Tin (Sn) Lead finish
- ◇ Cathode Band / Device marking
- ◇ Surface Mount Package Ideally Suited for Automatic Insertion



Maximum Ratings (T_a = 25 °C)

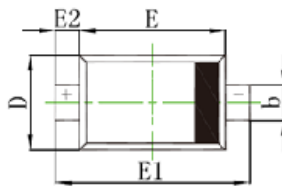
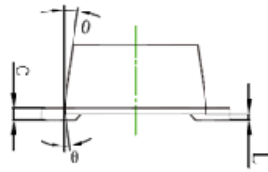
Symbol	Parameter	Value	Units
V _{RRM}	Peak Repetive Reverse Voltage	30	V
V _{RWM}	Working Peak Reverse Voltage	30	V
V _R	DC Blocking Voltage	30	V
V _{R(RMS)}	RMS Reverse Voltage	28	V
I _{FM}	Forward Continuous Current	350	mA
I _{FSM}	Non-Repetitive Peak Forward Surge Current (@t=8..3ms)	2.0	A
P _D	Power Dissipation	200	mW
T _J	Junction Temperature	125	°C
T _{STG}	Storage Temperature	-55 to +150	°C
R _{θJA}	Thermal Resistance From Junction To Ambient	625	°C/W

Electrical Characteristics (T_a = 25 °C)

Symbol	Parameter	Conditions	Min	Max	Units
V _{BR}	Reverse Voltage	I _F = 100uA	30		V
V _F	Forward Voltage	I _F = 20mA		0.37	V
		I _F = 200mA		0.60	V
I _R	Reverse current	V _R = 30V		5	μ A
C _T	Capacitance	V _R = 0V, f = 1MHz		50	pF
t _{rr}	Reverse Recovery Time	I _F = I _R = 50mA, R _L = 100 Ω		4	ns

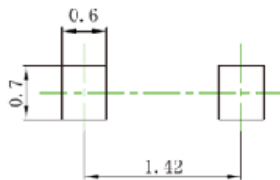
Package Dimensions

Package outline : SOD-523



Unit	A	A1	b	c	D	E	E1	E2	L	θ
Max.	0.77	0.70	0.35	0.15	0.85	1.30	1.70	0.20	0.07	7°
Min.	0.51	0.50	0.25	0.08	0.75	1.10	1.50	REF.	0.01	REF.

SOD-523 Package Outline



Lead Pattern Recommendation

Note:

1. Halogen free, EMC
2. Pb free solder
3. Lead thickness includes solder plating
4. Lead frame: Cu
5. Other Tolerance: ± 0.05
6. Dimensions are exclusive of Burrs, Mold Flash and Tie Bar extrusions
7. Unit: mm